| ABBOGIATION CONNECTING<br>LECTRONICS INDUSTRIES® INCOMPLETING | PC, Bannockt                                      | ourn, Illinois. A          | All rights reserved untions. | nder both               | This docum<br>level parts, t | ent is a declara<br>he declaration                                  | tion of the s<br>encompasse                    | ubstances<br>es all lower | within the manufactur<br>r level materials for w | rer listed in<br>hich the m     | tem. Note: if<br>nanufacturer | f the item is an as<br>has engineering | sembly with lower responsibility. |  |
|---|---|----------------------------|------------------------------|-------------------------|------------------------------|---|--|---------------------------|--|---------------------------------|-------------------------------|--|-----------------------------------|--|
|   |   |                            |                              | Form Type<br>Distribute | e *                          | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materia |  |                           |  | als and Mfg Information         |                               |  |                                   |  |
| Supplier Information  |   |                            |                              |                         |                              |   |  |                           |  |                                 |                               |  |                                   |  |
| Company name* Compan  |   |                            | mpany unique ID              |                         |                              | Unique ID Authority   |  |                           |  | Response Date*                  |                               |  |                                   |  |
| onsemi  |   |                            |                              |                         |                              |   |  |                           |  | 2025-07-03                      |                               |  |                                   |  |
| Contact Name Title - Contact                                  |   |                            | ct                           | 1                       |                              |   | Phone - Contact*                               |                           |  |                                 | Email - Contact*              |  |                                   |  |
| Product-Env-Stewards Product Env                              |   |                            | Enviro Compliance            |                         |                              | NA  |  |                           |  | Product-Env-Stewards@onsemi.com |                               |  |                                   |  |
| Authorized Representative* Title - Represe                    |   |                            | esentative                   |                         |                              | Phone - Representative*   |  |                           | Email - Representative*                          |                                 |                               |  |                                   |  |
| Product-Env-Stewards Product E                                |   |                            | oduct Enviro Compliance      |                         |                              | NA  |  |                           |  | Product-Env-Stewards@onsemi.com |                               |  |                                   |  |
| Requester Item Number   | Mfr Item  | Number                     | Mfr Item Name                |                         |                              | Effective Dat   | e Version                                      | N                         | Manufacturing Site                               |                                 | Weight*                       | UOM                                    | Unit Type                         |  |
|   | MBRD6   | IBRD660CTRLG REC DPAK 6A 6 |                              | OV SHTKY TR             | R                            | 2025-07-03  |  | N                         | MY1  |                                 | 350.99                        | mg                                     | Each                              |  |
| Manufacturing Proccess Informa                                | tion  |                            |                              |                         |                              |   | -  |                           |  | ł                               |                               |  |                                   |  |
| Terminal Plating / Grid Array M                               | nal Plating / Grid Array Material Terminal Base A |                            | Alloy                        | J-STD-020 MSL Rating F  |                              | Peak Pro  | Peak Process Body Temperature Max Time at Peak |                           | Temperature Number of Reflow Cycles              |                                 |                               |  |                                   |  |
| Matte Tin (Sn) - annealed CU Alloy                            |   | CU Alloy                   |                              | 1                       |                              | 260   |  | C                         | 30   | secon                           | ds 3                          |  |                                   |  |
| Comments  |   |                            |                              |                         |                              |   |  |                           |  |                                 |                               |  |                                   |  |
| level 1 - maximum time at peak temperatu                      | ure during sol                                    | ldering is 10-3            | 0 seconds                    |                         |                              |   |  |                           |  |                                 |                               |  |                                   |  |
| For more information regarding material                       | composition                                       | please refer to            | page 3                       |                         |                              |   |  |                           |  |                                 |                               |  |                                   |  |

| RoHS Material Composition Declaration  |   |  |              | Declaration Type *                              | Detailed                                     |  |  |  |  |  |  |
|--|---|--|--------------|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | (Pb), Mercury (Hg), Hexavalent Chro       | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |              |   |  |  |  |  |  |  |  |
| Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury,<br>cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part<br>contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall<br>encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief,<br>is of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive.<br>Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not<br>ndependently verified information provided by others, Supplier agrees that, at a minimum, itssuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the<br>sertification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of<br>hat agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provid |   |  |              |   |  |  |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst | ances per the definition above except for sele   | ected exempt | ions Supplier Acceptance                        | * Accepted                                   |  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol | der alloys containing 85% by weight or m   | ore lead).   |   |  |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU                            |  |              |   |  |  |  |  |  |  |  |
| Declaration Signature  |   |  |              |   |  |  |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |   |  | e drop-dowi  | a. This will display the signature area. Digita | lly sign the declaration (if required by the |  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska                            | Le   |              |   |  |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance               | CAS              | Exempt | Weight   | Unit of Measure |
|----------------------|--------|-----------------|----------|-------------------------|------------------|--------|----------|-----------------|
| Die                  | 0.2    | mg              | Supplier | Silicon (Si)            | 7440-21-3        |        | 0.2      | mg              |
| Die Attach           | 1.4    | mg              | А        | Lead (Pb)               | 7439-92-1        | 7a     | 1.33     | mg              |
|                      |        |                 | Supplier | Tin (Sn)                | 7440-31-5        |        | 0.07     | mg              |
| Lead Frame           | 214.64 | mg              | В        | Nickel (Ni)             | 7440-02-0        |        | 0.4293   | mg              |
|                      |        |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 214.2107 | mg              |
| Mold Compound-Black  | 129.65 | mg              |          | Epoxy resin             | proprietary data |        | 9.0755   | mg              |
|                      |        |                 | Supplier | Phenolic Resin          | Proprietary Data |        | 3.8895   | mg              |
|                      |        |                 | Supplier | Silica Amorphous (SiO2) | 7631-86-9        |        | 12.965   | mg              |
|                      |        |                 | Supplier | Carbon Black (C)        | 1333-86-4        |        | 0.6482   | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)     | 60676-86-0       |        | 103.0717 | mg              |
| Plating              | 3.73   | mg              | Supplier | Tin (Sn)                | 7440-31-5        |        | 3.73     | mg              |
| Wire Bond - Al       | 1.37   | mg              | Supplier | Aluminum (Al)           | 7429-90-5        |        | 1.37     | mg              |

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signar range of distribution unless otherwise noted)